



### General Specifications

|                           |                             |
|---------------------------|-----------------------------|
| <b>Resistive Element:</b> | Thick film                  |
| <b>Substrate:</b>         | Aluminum nitride ceramic    |
| <b>Terminals:</b>         | Tin/Lead, 90/10 over nickel |

### Electrical Specifications

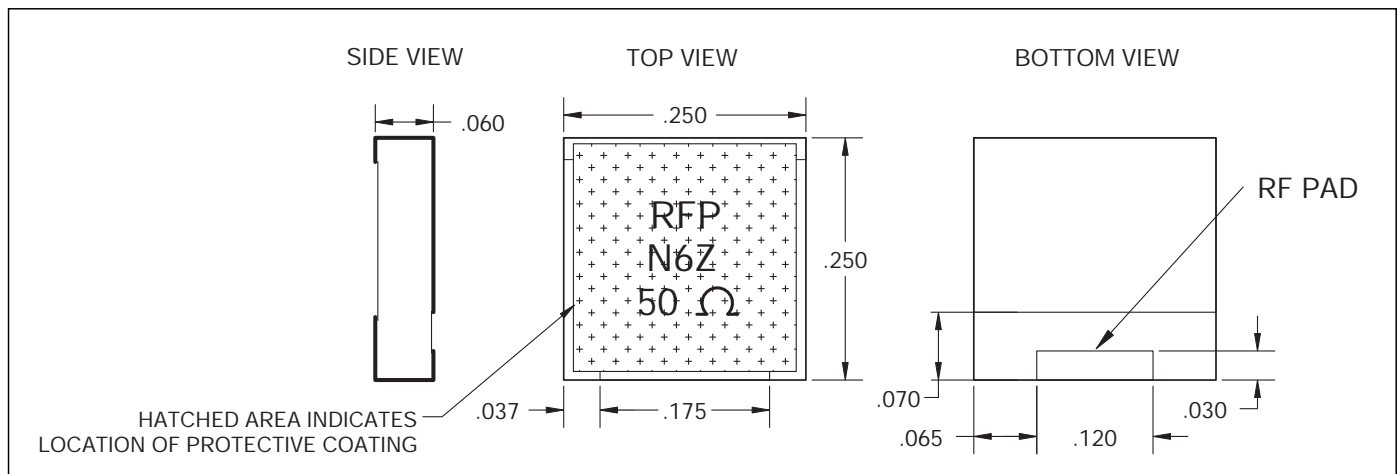
|                          |                    |
|--------------------------|--------------------|
| <b>Resistance Value:</b> | 50 ohms, $\pm 2\%$ |
| <b>Frequency Range:</b>  | DC - 3.0 GHz       |
| <b>Power:</b>            | 16 Watts           |
| <b>V.S.W.R.:</b>         | 1.25:1             |

**Notes:** Tolerance is  $\pm 0.10$ , unless otherwise specified. Operating temperature is  $-55^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$  (see chart). Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions are in inches. **Specifications subject to change without notice.**

### Features

- DC – 3.0 GHz
- 16 Watts
- Aluminum Nitride (AlN) Ceramic
- Surface Mountable
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

### Outline Drawing



VER. 12/5/01



Available on Tape and Reel for Pick and Place Manufacturing.

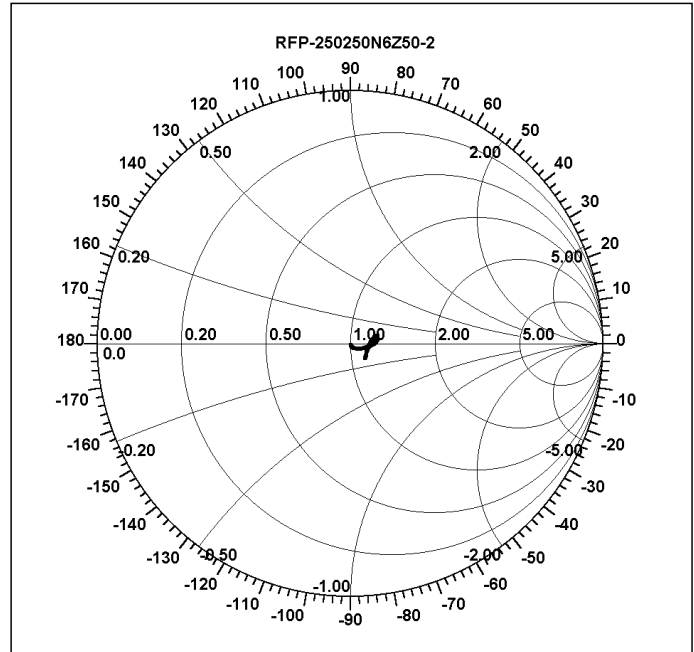
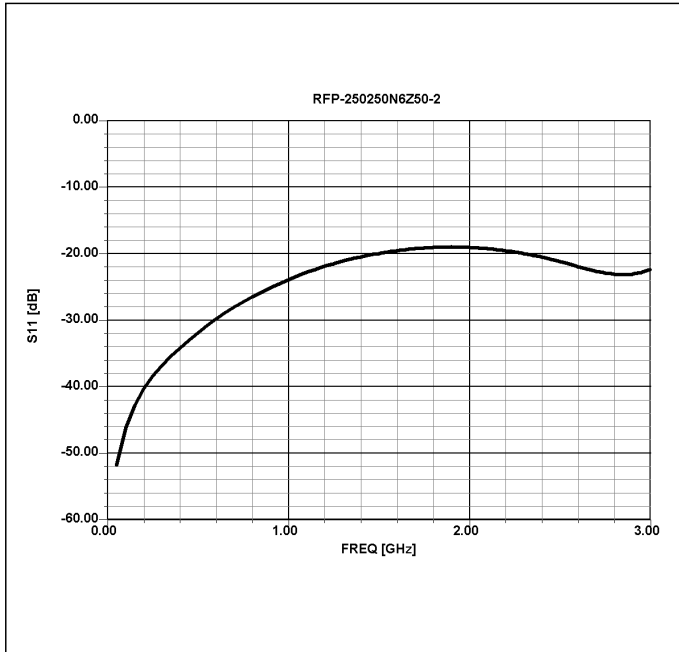
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# Model RFP-250250N6Z50-2

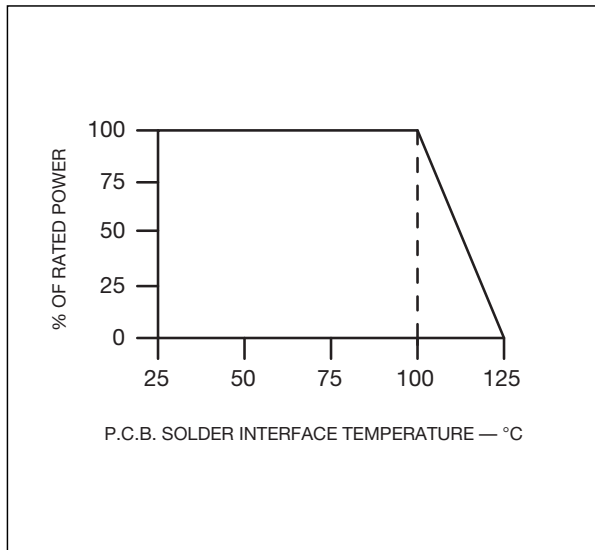


**RF Power**

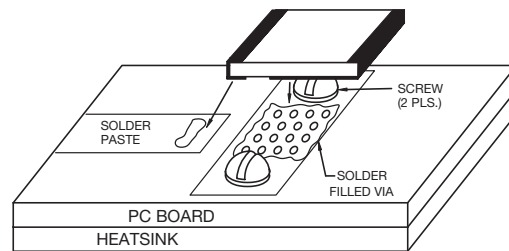
## Typical Performance



## Power Derating



## Suggested Mounting Procedures



1. Solder part in place using 60/40 type solder with controlled temperature iron (700°F).
2. Drill thermal via through PCB and fill with solder, such as 60/40 type.
3. To ensure good thermal connectivity to heat sink, drill and tap heatsink and mount PCB board to heat sink using screws.

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